



PK608 (v1.0) May 17, 2013

100% Material Declaration Data Sheet for Kintex[®]-7 Device FB484 Package

Average Weight: 2.0928 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.182430	8.717
	Silicon	7440-21-3	100.00		0.182430	
Solder Bump					0.008874	0.424
	Tin	7440-31-5	63.00		0.005591	
	Lead	7439-92-1	37.00		0.003283	
Underfill					0.030000	1.434
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00		0.006000	
	Phenolic resin	Trade Secret	15.00		0.004500	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00		0.001500	
	Amine type accelerator	Trade Secret	5.00		0.001500	
	Silicon dioxide	60676-86-0	51.50		0.015450	
	Carbon black	1333-86-4	1.00		0.000300	
	Additives	Trade Secret	2.50		0.000750	
Solder Paste					0.002804	0.134
	Tin	7440-31-5	96.50		0.002706	
	Silver	7440-22-4	3.00		0.000084	
	Copper	7440-50-8	0.50		0.000014	
Solder Ball					0.460670	22.013
	Tin	7440-31-5	63.00		0.290222	
	Lead	7439-92-1	37.00		0.170448	
Capacitor 1					0.010800	0.516
	BaTiO ₃ type	12047-27-7	70.60	Ceramic	0.007625	
	Ni	7440-02-0	6.70	Inner electrode	0.000724	
	Cu	7440-50-8	20.10	Out electrode	0.002171	
	Ni	7440-02-0	0.80	Plating1	0.000086	
Sn	7440-31-5	1.80	Plating2	0.000194		

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Capacitor 2					0.000600	0.029
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.000396	
	Ni	7440-02-0	2.67	Inner Electrode	0.000016	
	Cu	7440-50-8	23.33	Outer Electrode	0.000140	
	Ni	7440-02-0	2.33	Plating1	0.000014	
	Sn	7440-31-5	5.67	Plating2	0.000034	
Capacitor 3					0.005580	0.267
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.002851	
	Ni	7440-02-0	27.00	Inner Electrode	0.001507	
	Cu	7440-50-8	16.00	Outer Electrode	0.000893	
	Glass	65997-17-3	0.90		0.000050	
	Ni	7440-02-0	2.00	Plating1	0.000112	
	Sn	7440-31-5	3.00	Plating2	0.000167	
Substrate					1.390997	66.467
	Copper	7440-50-8	37.32		0.519064	
	Tin	7440-31-5	1.04		0.014533	
	Lead	7439-92-1	0.22		0.003054	
	Silver	7440-22-4	0.02		0.000290	
	BT Core	N/A	47.87		0.665849	
	ABF	N/A	11.10		0.154440	
	Solder Mask	N/A	2.43		0.033767	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/17/2013	1.0	Xilinx Initial Release

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